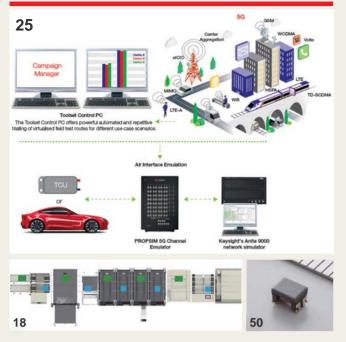


Asia Electronics Industry June 2020 Volume 25, Serial No. 285



	6	AEI NEWS	08
	0	IN VIEW THIS MONTH	10
		BUSINESS STRATEGY	54
	~	PRODUCT NEWS	57

DEPARTMENTS

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@ dempa.co.jp; Subscription e-mail: circulationmanila@dempa.co.jp.

The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at https://www.dempa.co.jp/en/pdfs/orderform.pdf

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TAIWAN: International Dempa Trade Co. Ltd.,7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559 KOREA: Dempa Publications, Room 1019, Punglim VIP Tel, 404, Gongdeuk-dong, Mapo, Seoul, Korea 04144, Tel: +82-2-714-2984 PHILIPPINES: Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-8845-0906 Fax: +63-2-8845-1829

President & Publisher: Tsutomu Hirayama Copyright © 2020 by Dempa Publications, Inc.

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SPECIAL REPORT

Panasonic Rethinks Manufacturing to Handle		
Micro-Components	14	
FUJI Fortifies Portfolio to Effect Full Smart Factory	. 16	

TECH FOCUS

Data Explosion Spurs Chip Industry to Ramp-up	
Memory Technologies	_ 1
Flow Splitter Technology Suits Leading-Edge Chip	
Manufacturing Process	_ 2
LINTEC's "Tape x Equipment" Promote Large-Capacity	
Thin Packages	_ 2
Keysight's Virtual Test Kit Propels Autonomous Driving	_ 2
Color Conversion Technology Emerges for Micro LEDs	

COMPONENT MATERIA	ALS	28
MOBILITY		32
SMTs: IN REVIEW		34

TEST AND MEASUREMENT

TECHNOLOGY HIGHLIGHT

Film Coating Technology Prevents Reduction	
of Solar Cell Power	40
Molecule Design Controls Crystal Structure	
of Organic Semiconductor	41

PRODUCT HIGHLIGHT

MEMS LiDAR Solution Exhibits Precise Scanning	
for Autonomous Vehicles	42
Robust Car Connectors Cater to Internal,	
	43
KEL Launches High-Performance Coaxial Harnesses	
Mouser Stocks up Intel's Next-Gen Wireless Modules	45

INDUSTRY REPORT

Innovations of Electronic Materials	Gather Momentum	46
--	-----------------	----

IN THE KNOW

Wireless, Measurement Technologies to Bolster	
IoT to Mainstream	48

ZOOM-IN

Demand Surges for High Heat-Re for Automotive	= 0
TAIWAN SPECIAL	52
SHOW REPORT	
Automotive World 2020	56

37